24-Stage Frequency Divider

The MC14521B consists of a chain of 24 flip–flops with an input circuit that allows three modes of operation. The input will function as a crystal oscillator, an RC oscillator, or as an input buffer for an external oscillator. Each flip–flop divides the frequency of the previous flip–flop by two, consequently this part will count up to $2^{24} = 16,777,216$. The count advances on the negative going edge of the clock. The outputs of the last seven–stages are available for added flexibility.

- All Stages are Resettable
- Reset Disables the RC Oscillator for Low Standby Power Drain
- RC and Crystal Oscillator Outputs Are Capable of Driving External Loads
- Test Mode to Reduce Test Time
- V_{DD}' and V_{SS}' Pins Brought Out on Crystal Oscillator Inverter to Allow the Connection of External Resistors for Low–Power Operation
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low–power TTL Loads or One Low–power Schottky TTL Load over the Rated Temperature Range.

MAXIMUM RATINGS (Voltages Referenced to V_{SS}) (Note 2.)

Symbol	Parameter	Value	Unit
V _{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	V
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 3.)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

2. Maximum Ratings are those values beyond which damage to the device may occur.

3. Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}.$

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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		MARKING DIAGRAMS
	PDIP-16 P SUFFIX CASE 648	16 MC14521BCP AWLYYWW
- BERERARD	SOIC-16 D SUFFIX CASE 751B	16 14521B ○ AWLYWW 1 1
PARTA AND	SOEIAJ-16 F SUFFIX CASE 966	16 MC14521B AWLYWW 1
A WL or I	= Assembly	

 $\begin{array}{l} A &= Assembly Location \\ WL or L &= Wafer Lot \\ YY or Y &= Year \\ WW or W &= Work Week \end{array}$

ORDERING INFORMATION

Device	Package	Shipping
MC14521BCP	PDIP-16	2000/Box
MC14521BD	SOIC-16	48/Rail
MC14521BDR2	SOIC-16	2500/Tape & Reel
MC14521BF	SOEIAJ-16	See Note 1.
MC14521BFEL	SOEIAJ-16	See Note 1.
MC14521BFR2	SOEIAJ-16	See Note 1.

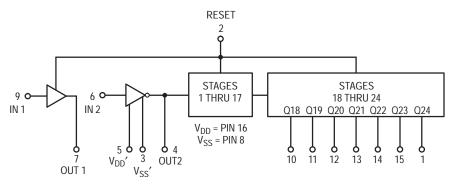
 For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

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PIN ASSIGNMENT

Q24 [1•	16	VDD
RESET [2	15] Q23
v _{ss} ' [3	14	022
OUT 2 [4	13	Q21
V _{DD} ′ [5	12	Q20
IN 2 [6	11	Q19
d	7	10	Q18
v _{ss} [8	9] IN 1

BLOCK DIAGRAM



Output	Count Capacity
Q18	2 ¹⁸ = 262,144
Q19	2 ¹⁹ = 524,288
Q20	2 ²⁰ = 1,048,576
Q21	2 ²¹ = 2,097,152
Q22	2 ²² = 4,194,304
Q23	2 ²³ = 8,388,608
Q24	2 ²⁴ = 16,777,216

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

		V _{DD}	C			25°C			125°C	
Characteristic	Symbol	Vdc	Min	Max	Min	Тур ^(4.)	Max	Min	Max	Unit
Output Voltage "0" Level $V_{in} = V_{DD}$ or 0	V _{OL}	5.0 10 15		0.05 0.05 0.05		0 0 0	0.05 0.05 0.05		0.05 0.05 0.05	Vdc
"1" Level V_{in} = 0 or V_{DD}	V _{OH}	5.0 10 15	4.95 9.95 14.95		4.95 9.95 14.95	5.0 10 15		4.95 9.95 14.95		Vdc
$\label{eq:VO} \begin{array}{ll} \mbox{Input Voltage} & "0" \mbox{Level} \\ (V_O = 4.5 \mbox{ or } 0.5 \mbox{ Vdc}) \\ (V_O = 9.0 \mbox{ or } 1.0 \mbox{ Vdc}) \\ (V_O = 13.5 \mbox{ or } 1.5 \mbox{ Vdc}) \end{array}$	V _{IL}	5.0 10 15		1.5 3.0 4.0		2.25 4.50 6.75	1.5 3.0 4.0		1.5 3.0 4.0	Vdc
"1" Level ($V_O = 0.5 \text{ or } 4.5 \text{ Vdc}$) ($V_O = 1.0 \text{ or } 9.0 \text{ Vdc}$) ($V_O = 1.5 \text{ or } 13.5 \text{ Vdc}$)	V _{IH}	5.0 10 15	3.5 7.0 11		3.5 7.0 11	2.75 5.50 8.25		3.5 7.0 11		Vdc
$\begin{array}{llllllllllllllllllllllllllllllllllll$	Іон	5.0 5.0 10 15	- 1.2 - 0.25 - 0.62 - 1.8	 	- 1.0 - 0.2 - 0.5 - 1.5	- 1.7 - 0.36 - 0.9 - 3.5	 	- 0.7 - 0.14 - 0.35 - 1.1	 	mAdc
$\begin{array}{ll} (V_{OH} = 2.5 \; Vdc) & Source \\ (V_{OH} = 4.6 \; Vdc) & Pins \; 1, \; 10, \\ (V_{OH} = 9.5 \; Vdc) & 11, \; 12, \; 13, \; 14 \\ (V_{OH} = 13.5 \; Vdc) & and \; 15 \end{array}$		5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	 	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	 	- 1.7 - 0.36 - 0.9 - 2.4	 	mAdc
	I _{OL}	5.0 10 15	0.64 1.6 4.2		0.51 1.3 3.4	0.88 2.25 8.8		0.36 0.9 2.4		mAdc
Input Current	l _{in}	15	—	± 0.1	-	±0.00001	± 0.1	-	± 1.0	μAdc
Input Capacitance (V _{in} = 0)	C _{in}	_	-	—	-	5.0	7.5	—	-	pF
Quiescent Current (Per Package)	I _{DD}	5.0 10 15		5.0 10 20		0.005 0.010 0.015	5.0 10 20		150 300 600	μAdc
Total Supply Current ^(5.) (6.) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)	ΙŢ	5.0 10 15			$I_{T} = (0$.42 μA/kHz) .85 μA/kHz) .40 μA/kHz)	f + I _{DD}			μAdc

4. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

The formulas given are for the typical characteristics only at 25°C.
To calculate total supply current at loads other than 50 pF:

 $I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$

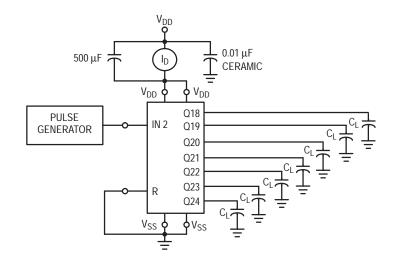
where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.003.

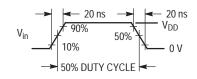
SWITCHING CHARACTERISTICS (7.) ($C_L = 50 \text{ pF}, T_A = 25^{\circ}C$)

Characteristic	Symbol	V _{DD} Vdc	Min	Тур ^(8.)	Мах	Unit
Output Rise and Fall Time (Counter Outputs) t_{TLH} , $t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ t_{TLH} , $t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ t_{TLH} , $t_{THL} = (0.55 \text{ ns/pF}) C_L + 12.5 \text{ ns}$	t _{TLH} , t _{THL}	5.0 10 15		100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q18 $t_{PHL}, t_{PLH} = (1.7 \text{ ns/pF}) C_L + 4415 \text{ ns}$ $t_{PHL}, t_{PLH} = (0.66 \text{ ns/pF}) C_L + 1667 \text{ ns}$ $t_{PHL}, t_{PLH} = (0.5 \text{ ns/pF}) C_L + 1275 \text{ ns}$	t _{PHL} , t _{PLH}	5.0 10 15	 	4.5 1.7 1.3	9.0 3.5 2.7	μs
Clock to Q24 t_{PHL} , $t_{PLH} = (1.7 \text{ ns/pF}) C_L + 5915 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.66 \text{ ns/pF}) C_L + 2167 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.5 \text{ ns/pF}) C_L + 1675 \text{ ns}$		5.0 10 15		6.0 2.2 1.7	12 4.5 3.5	
Propagation Delay Time Reset to Q_n $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 1215 \text{ ns}$ $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 467 \text{ ns}$ $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 350 \text{ ns}$	t _{PHL}	5.0 10 15	 	1300 500 375	2600 1000 750	ns
Clock Pulse Width	t _{WH(cl)}	5.0 10 15	385 150 120	140 55 40		ns
Clock Pulse Frequency	f _{cl}	5.0 10 15	 	3.5 9.0 12	2.0 5.0 6.5	MHz
Clock Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15			15 5.0 4.0	μs
Reset Pulse Width	t _{WH(R)}	5.0 10 15	1400 600 450	700 300 225		ns
Reset Removal Time	t _{rem}	5.0 10 15	30 0 - 40	- 200 - 160 - 110		ns

7. The formulas given are for the typical characteristics only at 25° C.

8. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.







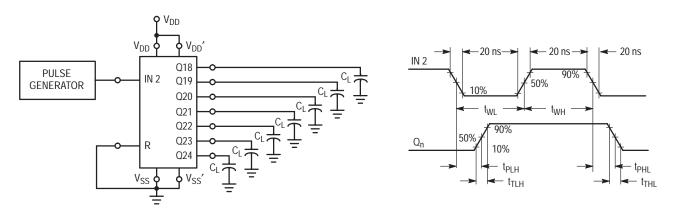
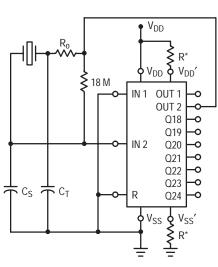


Figure 2. Switching Time Test Circuit and Waveforms



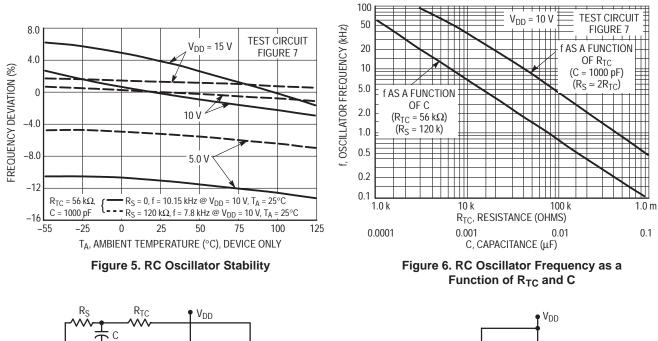
* Optional for low power operation, 10 k $\Omega \leq R \leq$ 70 k $\Omega.$



Characteristic	500 kHz Circuit	50 kHz Circuit	Unit
Crystal Characteristics Resonant Frequency Equivalent Resistance, R _S	500 1.0	50 6.2	kHz kΩ
External Resistor/Capacitor Values R _o C _T C _S	47 82 20	750 82 20	kΩ pF pF
Frequency Stability Frequency Change as a Function of V_{DD} ($T_A = 25^{\circ}$ C) V_{DD} Change from 5.0 V to 10 V V_{DD} Change from 10 V to 15 V Frequency Change as a Function of Temperature ($V_{DD} = 10$ V) T_A Change from -55° C to $+25^{\circ}$ C	+ 6.0 + 2.0 - 4.0	+ 2.0 + 2.0 - 2.0	ppm ppm ppm
MC14521 only Complete Oscillator* T _A Change from +25°C to+125°C MC14521 only	+ 100	+ 120	ppm
Complete Oscillator*	- 160	- 560	ppm

*Complete oscillator includes crystal, capacitors, and resistors.

Figure 4. Typical Data for Crystal Oscillator Circuit



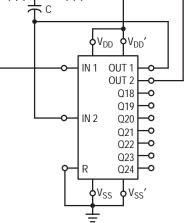


Figure 7. RC Oscillator Circuit

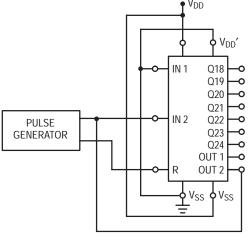
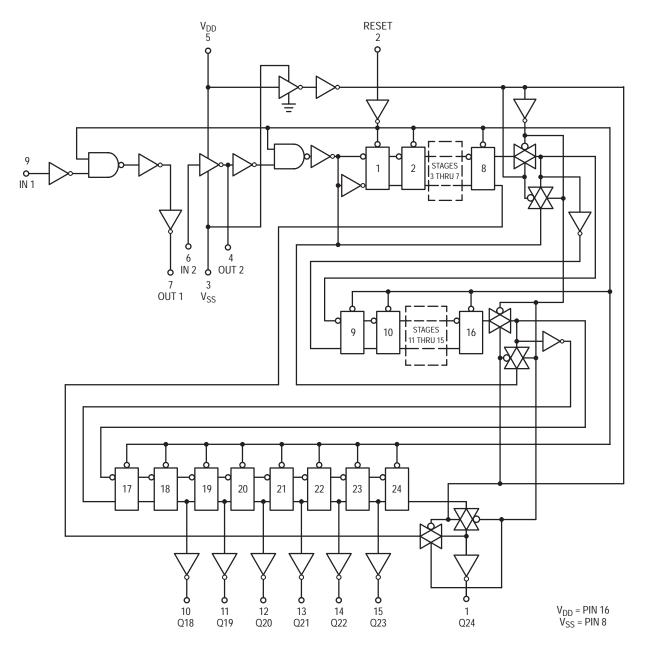


Figure 8. Functional Test Circuit

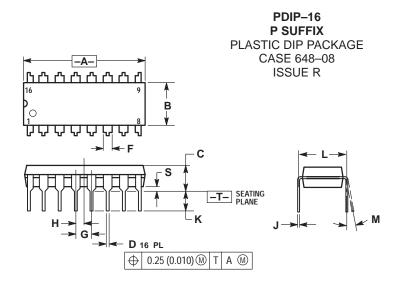
FUNCTIONAL TEST SEQUENCE

	Inp	nputs Outputs				Comments	
	Reset	ln 2	Out 2	V _{SS} ′	V _{DD} '	Q18 thru Q24	Counter is in three 8–stage sections in parallel mode Counter is reset. In 2 and
	1	0	0	V _{DD}	Gnd	0	Out 2 are connected together
A test function (see Figure 8) has been included for the reduction of test time required to	0	1	1				First "0" to "1" transition on In 2, Out 2 node.
exercise all 24 counter stages. This test function divides the counter into three 8–stage sections,		0 1	0 1				255 "0" to "1" transitions are clocked into this In 2,
and 255 counts are loaded in each of the 8-stage sections in parallel. All flip-flops are now at a logic "1". The counter is now returned			_ _ _				Out 2 node.
to the normal 24-stages in series configuration. One more pulse is entered into Input 2 (In 2)		1	1			1	The 255th "0" to "1" transition.
which will cause the counter to ripple from an all "1" state to an all "0" state.		0 0	0 0			1 1	
		1	0	Gnd	V _{DD}	1	Counter converted back to 24–stages in series mode.
		1	0			1	Out 2 converts back to an output.
	V	0	1	V		0	Counter ripples from an all "1" state to an all "0" stage.

LOGIC DIAGRAM



PACKAGE DIMENSIONS



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL. 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH. 5. POLINDED CORNERS OPTIONAL.

5. F	ROUNDED CORNERS OPTIONAL.							
		INC	HES	MILLIN	IETERS			
	DIM	MIN MAX		MIN	MAX			
	Α	0.740	0.770	18.80	19.55			
	В	0.250	0.270	6.35	6.85			
	С	0.145	0.175	3.69	4.44			
	D	0.015	0.021	0.39	0.53			
	F	0.040	0.70	1.02	1.77			
	G	0.100	0.100 BSC		BSC			
	Н	0.050 BSC		1.27	BSC			
	J	0.008	0.015	0.21	0.38			
	К	0.110	0.130	2.80	3.30			
		0.005	0.005	7.50	7.74			

L 0.295 0.305 M 0° 10°

S 0.020 0.040

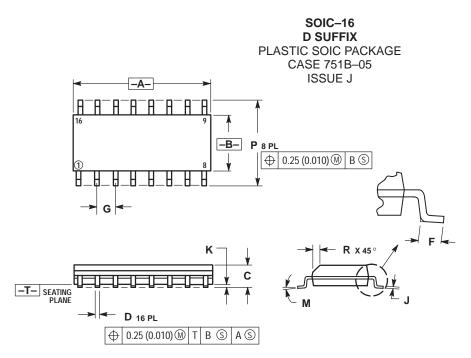
3.30 7.74 10 °

1.01

2.80 7.50 0 °

0.51

PACKAGE DIMENSIONS



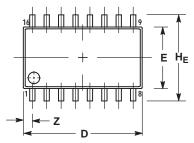
NOTES:

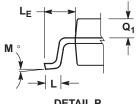
- 1. DIMENSIONING AND TOLERANCING PER ANSI
- 2. 3.
- 4.
- DIMENSIONING AND TOLERANCING PER ANS Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. 5.

	MILLIN	IETERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α	9.80	10.00	0.386	0.393		
В	3.80	4.00	0.150	0.157		
С	1.35	1.75	0.054	0.068		
D	0.35	0.49	0.014	0.019		
F	0.40	1.25	0.016	0.049		
G	1.27	BSC	0.050 BSC			
J	0.19	0.25	0.008	0.009		
К	0.10	0.25	0.004	0.009		
Μ	0°	7°	0°	7°		
Р	5.80	6.20	0.229	0.244		
R	0.25	0.50	0.010	0.019		

PACKAGE DIMENSIONS

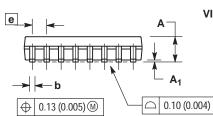
SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE CASE 966-01 ISSUE O

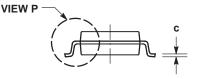




DETAIL P

A





NOTES:

DIMENSIONING AND TOLERANCING PER ANSI 1.

211 DIMENSIONING AND TOLERANGING PERF 214.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE

MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. 4. TERMINAL NUMBERS ARE SHOWN FOR

 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BF 0.46 (0.018). TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050 BSC	
Η _E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
М	0 °	10 °	0 °	10 °
Q ₁	0.70	0.90	0.028	0.035
Ζ		0.78		0.031

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